

**TRANSMITTAL OF INFORMATION DISCLOSURE STATEMENT**  
(Under 37 CFR 1.97(b) or 1.97(c))

Docket No.  
OKI.244

In Re Application Of: **Ken Ogura**

Serial No.  
NEW

Filing Date  
JUNE 19, 2001

Examiner  
TO BE ASSIGNED

Group Art Unit  
TO BE ASSIGNED

Title: **CONDUCTOR POSTS, CONSTRUCTION FOR AND METHOD OF FABRICATING SEMICONDUCTOR INTEGRATED CIRCUIT CHIPS USING THE CONDUCTOR POST, AND METHOD OF PROBING SEMICONDUCTOR INTEGRATED CIRCUIT CHIPS**

Address to:

**Assistant Commissioner for Patents  
Washington, D.C. 20231**

**37 CFR 1.97(b)**

1. ☒ The Information Disclosure Statement submitted herewith is being filed within three months of the filing of a national application; within three months of the date of entry of the national stage as set forth in 37 CFR 1.491 in an international application; or before the mailing date of a first Office Action on the merits, whichever event occurs last.

**37 CFR 1.97(c)**

2. ☐ The Information Disclosure Statement submitted herewith is being filed after three months of the filing of a national application, or the date of entry of the national stage as set forth in 37 CFR 1.491 in an international application; or after the mailing date of a first Office Action on the merits, whichever occurred last but before the mailing date of either:

1. a Final Action under 37 CFR 1.113, or
2. a Notice of Allowance under 37 CFR 1.311,

whichever occurs first.

Also submitted herewith is:

- ☐ a certification as specified in 37 CFR 1.97(e);

**OR**

- ☐ the fee set forth in 37 CFR 1.17(p) for submission of an Information Disclosure Statement under 37 CFR 1.97(c).

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**Payment of Fee**

(Only complete if Applicant elects to pay the fee set forth in 37 CFR 1.17(p))

- ☐ A check in the amount of \_\_\_\_\_ is attached.
- ☐ The Assistant Commissioner is hereby authorized to charge and credit Deposit Account No. \_\_\_\_\_ as described below. A duplicate copy of this sheet is enclosed.
- ☐ Charge the amount of \_\_\_\_\_
- ☐ Credit any overpayment.
- ☐ Charge any additional fee required.

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Signature

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REG. NO. 33289

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TEL. NO. (703) 715-0870

CC:

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Typed or Printed Name of Person Mailing Correspondence

Dated: JUNE 19, 2001